

## **TECHNICAL SPEC FOR CMP tool**

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**System Model:**  
**Cybeq 8000**

**Process: Oxide**

**Substrate size: 6 inch**

**Wet stage loaders: Wafer loading module, custom designed load and unload system containing 4 cassette nests and 2 Cybeq articulated robots**

**Chemicals / gases used: Klebosol & DI water**

**Polisher controller: head speed controller SC400 servocontroller**

**Platen assemblies: 36" diameter, 304stainless steel with coating. Platen & carousel controller SC750series**

**Pad conditioner assemblies: pad dresser**

**Slurry distribution motors and arm assemblies: ASSY 0162-5088 slurry pump drive/head**

**Polishing heads: 6 floating head wafer carriers**

**Head cleaning loading and unloading unit (HCLU):**

**Loaders: wafer handling up to 200mm in diameter, 2 Cybeq 8000robots & 2 head loading modules (HLM)**

**Robot assembly: Cybeq 8000robot**

**Computer rack: Siemens PLCs for motion control**

**Metrology tools: NA**

**SW:**

**Missing parts: none**

**Defected parts:**

**Operating system: MS windows - GUI**